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Technical Literature For TFT-LCD Module

Model No. <u>LS027B4DH01</u>

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> Liquid Crystal Display Group SHARP CORPORATION



	RECORD	S OF REVISIO	N
DATE	REF.PAGE PARAGRAPH DRAWING No.	REVISED No.	SUMMARY
5 th November, 2009	Page7, Table3-1	1.0	To add weight value
5 th November, 2009	Page13, Table6-4	1.0	To modify power consumption Typical value of Condition1 and Condition 2
5th April, 2010	Page13, Table6-4	2.0	Updated power consumption Typical value of Condition1 and Condition 2
5th April, 2010	Page 18, 6-5-5 COM Inversion	2.0	In EXTMODE=H, the explanation for driving has been changed.
5th April, 2010	Page20, Table7-1	2.0	Updated optical characteristics (Reflection Ratio, Panel Surface Chromaticity)
5th April, 2010	Page26, 11-2 Package Storing	2.0	"Number of carton in a stock" and "Number of quantity of unit in carton" have been changed.
5th April, 2010	Page26, 11-3Package Storing	2.0	Packaging drawing has been changed.



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<<Precautions>>

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- Traffic signals
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[For handling and system design]

(1) Handle with care as glass is used in this LCD panel. Dropping or contact against hard object may cause cracks or chips.

(2) Be careful to handle this LCD panel in order to avoid injury yourself by panel's edge as this panel is made of glass and might be a sharp edge.

(3) Do not scratch the surface of the polarizer film as it is easily damaged.

(4) Water droplets on the polarizer film must be wiped off immediately as they may cause color changes, or other defects if remained for a long time.

(5)Do not leave the LCD panel in direct sun or under ultraviolet ray.

(6) To clean LCD panel surface, wipe clean with absorbent cotton or soft cloth. If further cleaning is needed, use IPA (isopropyl alcohol) and wipe clean lightly on surface only. Do not use organic solvents as it may damage the LCD panel terminal area which uses organic material. Also, do not directly touch with finger. When the terminals cleaning are needed, those should be wiped by a soft cloth or a cotton swab without directly touching by hand.

(7) Do not expose gate driver, etc. on the panel (circuit area outside panel display area) to light as it may not operate properly. Design that shields gate driver, etc. from light is required when mounting the LCD module.

(8) To avoid circuit failure, do not touch panel terminal area.

(9) Support for the LCD panel should be carefully designed to avoid stress that exceeds specification on glass surface.
(10) When handling LCD module and assembling them into cabinets, be noted that storage in the environment of oxidization or deoxidization gas and the use of such materials as reagent, solvent, adhesive, resin, and etc. which generate these gasses, may cause corrosion and discoloration of LCD modules.

(11)To avoid picture uniformity failure, do not put a seal or an adhesive material on the panel surface.

(12) Do not use chloroprene rubber as it generates chlorine gas and affects reliability in LCD panel connective area.

(13) Protective film is attached to the surface of polarizer film on LCD panel to prevent scratches or other damages. Remove this protective film before use. In addition, do not attach the protective film which is removed from LCD module again. When the LCD panel which has the reattached protective film is needed to storage for a long time, the polarizer film might have a damage with picture quality failure.

(14) Panel is susceptible to mechanical stress and such stress may affect the display. Place the panel on flat surface to avoid stress caused by twist, bend, etc.

(15) When transporting LCD panels, secure them in LCD panel tray to avoid mechanical stress. The tray should be conductive to protect LCD panels from static charge.

Material used in set or epoxy resin (amine type hardening agent) from packaging, and silicon adhesive (dealcoholized or oxime) all release gas which may affect quality of polarizer film. Do confirm compatibility with user materials.

(16) As this LCD module is composed electronic circuits, it is sensitive to electrostatic discharge of 200V or more.Handle with care using cautions for the followings:

Operators

Operators must wear anti-static wears to prevent electrostatic charge up to and discharge from human body.



• Equipment and containers

Process equipment such as conveyer, soldering iron, working bench and containers may possibly generate electrostatic charge up and discharge. Equipment must be grounded through 100Mohms resistance. Use ion blower.

Floor

Floor plays an important role in leaking static electricity generated in human body or equipment. If the floor is made of insulated material (such as polymer or rubber material), such static electricity may charge. Proper measure should be taken to avoid static electricity charge (electrostatic earth: 100Mohms). There is a possibility that the static electricity is charged to them without leakage in case of insulating floor, so the electrostatic earth: $1 \times 10^8 \Omega$ should be made.

Humidity

Humidity in work area relates to surface resistance of the persons or objects that generate electrostatics, and it can be manipulated to prevent electrostatic charge. Humidity of 40% or lower increases electrostatic earth resistance and promotes electrostatic charging. Therefore, the humidity in the work area should be kept above 40%. Specifically for film peeling process or processes that require human hands, humidity should be kept above 50% and use electricity removal blower.

• Transportation/Storage

Containers and styroform used in transporation and storage may charge electrostatic (from friction and peeling) or electrostatic charge from human body, etc. may cause containers and styroform to have induced charge. Proper electrostatic measure should be taken for containers and storage material.



[For operating LCD module]

(1) Do not operate the LCD panel under outside of electrical specification. Otherwise LCD panel may be damaged.

(2) Do not use the LCD panel under outside of specified driving timing chart. Otherwise LCD panel may not have proper picture quality.

(3) A still image should be displayed less than two hours, if it is necessary to display still image longer than two hour, display image data must be refreshed in order to avoid sticking image on LCD panel.

(4) If LCD module takes a static electricity, as the display image which is written into pixel memory might not be displayed, Data update should be executed frequently.

[Precautions for Storage]

(1) After opening the package, do not leave the LCD panel in direct sun or under strong ultraviolet ray. Store in dark place.

(2) In temperature lower than specified rating, liquid crystal material will coagulate. In temperature higher than specified rating, it isotropically liquifies. In either condition, the liquid crystal may not recover its original condition. Store the LCD panel in at or around room temperature as much as possible.

Also, storing the LCD panel in high humidity will damage the polarizer. Store in normal room temperature as much as possible.

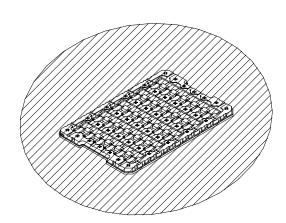
(3) Keeping Method

a. No direct sun light

b. Store in trays and in dark room









[Other Notice]

- (1) Operation outside specified environmental conditions cannot be guaranteed.
- (2) As power supply (VDD-GND, VDDA-GND) impedance is lowered during use, bus controller should be inserted near LCD module as much as possible.
- (3) Polarizer film is applied over LCD panel surface. Liquid crystal inside LCD panel deteriorates with ultraviolet ray. The panel should not be left in direct sun or under strong ultraviolet ray for prolonged period of time even with the polarizer film.
- (4) Disassembling the LCD module will cause permanent damage to the module. Do not disassemble the module.
- (5) If LCD panel is broken, do not ingest the liquid crystal from the broken panel. If hand, leg, or clothes come in contact with liquid crystal, wash off immediately with soap.
- (6) ODS (specific chlorofuorocarbon, specific halon, 1-1-1 trichloroethane, carbon tetrachloride) are not used or contained in material or all production processes of this product.
- (7) Observe all other precautionary requirements in handling general electronic components.

Discarding liquid crystal modules

- LCD Panel
 : Dispose of as glass waste. This LCD module contains no harmful substances. The liquid crystal panel contains no dangerous or harmful substances. This liquid crystal panel contains only an extremely small amount of liquid crystal (approximately 100mg) and therefore it will not leak even if the panel should break. Its median lethal dose (LD50) is greater than 2,000 mg/kg and a mutagenetic (Aims test: negative) material is used.
- FPC : (1) FPC bend R should be 0.45mm or greater and R should be even.
 In LCD panel an connective area, do not bend FPC into polarizer film side.
 (2) Do not hang LCD module by FPC or apply force to FPC.



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1. Scope of Application

Reflective active-matrix type memory liquid crystal display module with WQVGA (400x240) panel which uses CG silicon thin film transistor.

2. Overview

- 2.7" WQVGA monochrome HR-TFT reflective panel
- 400x240 dot stripe arrangement
- Display control with serial data signal communication
- · Arbitrary line data update
- · Internal 1bit memory within the panel for data memory
- · Thin, light and compact module with monolithic technology
- Super low power consumption TFT panel
- With FPC (Applicable connector: Refer to recommended connector on page 21.)

3. Mechanical Specification

Tabke 3-1 Module Mechanical Specification

Specification	Unit
6.86cm (2.7")	cm
58.8 (H) × 35.28 (V)	mm
400 (H) × 240 (V)	dot
0.147 (H) × 0.147 (V)	mm
Stripe arrangement	-
62.8 (W) × 42.82 (H) × 1.53 (D)	mm
9.4 (TYP)	g
3H or more (Initial)	Pencil hardness
	$\begin{array}{c} 6.86 \text{cm} (2.7") \\ \hline 58.8 (\text{H}) \times 35.28 (\text{V}) \\ 400 (\text{H}) \times 240 (\text{V}) \\ 0.147 (\text{H}) \times 0.147 (\text{V}) \\ \hline \text{Stripe arrangement} \\ \hline 62.8 (\text{W}) \times 42.82 (\text{H}) \times 1.53 (\text{D}) \\ \hline 9.4 (\text{TYP}) \end{array}$

(Remark) Refer to Figure 8-1 for detailed dimension and tolerance.



4. Input Terminal names and function

4-1) Input Terminal

Table 4	-1			
Terminal	Code	I/0	Function	Remark
1	SCLK	INPUT	Serial clock signal	
2	SI	INPUT	Serial input signal	
3	SCS	INPUT	Chip select signal	
4	EXTCOMIN	INPUT	External COM inversion signal input (H: Active)	
5	DISP	INPUT	Display ON/OFF signal	[Remark 4-2]
6	VDDA	POWER	Analalog power supply	
7	VDD	POWER	Digital power supply	
8	EXTMODE	INPUT	COM inversion mode switch terminal	【Remark 4-1】
9	VSS	POWER	Logic GND	
10	VSSA	POWER	Analog GND	

[Remark 4-1] "H"=EXTCOMIN singal enabled, "L"=Serial input flag enabled.

When "H", connect EXTMODE to VDD and when "L" to VSS.

[Remark 4-2] ON/OFF for LCD display only. Memory data is maintained.

When "H", displays with memory data, and when "L", displays all white with memory data maintained.

4-2) Recommended Circuit COM signal serial input EXTMODE="L"

> COM Signal Serial Input EXTMODE=L

	1	SCLK
	2	SI
	3	SCS
	4	EXTCOMIN
	5	DISP
	6	VDDA
	7	VDD
	8	EXTMODE
-	9	VSS
	10	VSSA

External COM signal input EXTMODE="H"

External COM Signal Input EXTMODE=H

 1	SCLK
 2	SI
 3	SCS
 4	EXTCOMIN
 5	DISP
 6	VDDA
 7	VDD
8	EXTMODE
 9	VSS
 10	VSSA



5. Absolute Maximum Rating

Table 5-1 (GND=0V)

	Item	Code	MIN.	MAX.	Unit	Remark
Power	Analog Power Supply	VDDA	-0.3	+5.8	V	
supply Voltage	Logic Power Supply	VDD	-0.3	+5.8	V	[Remark 5-1]
Input sign	al terminal voltage (high)			VDD	V	[Remark 5-2]
Input sign	al terminal voltage (low)		-0.3		V	
Storage te	emperature	Tstg	-30	+80	°C	[Remark 5-3,4]
Operating	temperature	Topr1	-20	+70	°C	[Remark 5-5]
(Panel su	rface temperature)					

[Remark 5-1] Also applicable to EXTMODE.

[Remark 5-2] Applicable to SCLK, SI, SCS, DISP, EXTCOMIN.

[Remark 5-3] Do not exceed this rating in any area of the module.

[Remark 5-4] Maximum wet-bulb temperature should be 57°C or lower. Do not allow condensation.

Condensation may cause electrical leak and the module may not meet s specification.

[Remark 5-5]Operating temperature is temperature that guarantess operation only. For contrast, response speed, and other display quty, module is evaluated at Ta=+25°C.

6. Electrical Characteristics

6-1) TFT LCD Panel Driving Part

 Table 7-1
 Recommended Operating Condition

 $VSS(GND) = 0V, Ta = +25^{\circ}C$

	Item	Code	MIN.	TYP.	MAX.	Unit	Remark
Power supply	Analog power Supply	VDDA	+4.8	+5.0	+5.5	V	
voltage	Logi power supply	VDD	+4.8	+5.0	+5.5	V	【Remark 6-1】
Input singal	Hi	VIH	+2.70	+3.00	₩VDD	V	【Remark 6-2】
voltage	Lo	VIL	VSS	VSS	VSS+0.15	V	

%Can operate below VDD voltage, however, operation around 3V is recommended.

[Remark 6-1] Also applicable to EXTMODE="H".

[Remark 6-2] Applies to SCLK, SI, SCS, DISP, EXTCOMIN.

		On St	equence	Normal or	peration		Offseque	ence			
	ļ		→	Normaro				•			
		1 2	3%14%1	ļ	}	5	6	7			
	ı L		T3 T4		1	T5	T6				
VDD/VDDA(5V)	GND			1		1			GND		
DISP	GND	1							GND		
EXTCOMIN	GND			Normal	operation	1			GND		
		×2		Normal		*2	1	1	1		
SCS	GND	*2		INOIMAI	operation	%Z		1	GND		
Others	GND	*2		Normal	operation	₩2			GND		
	1	I	<u> </u>	l I		l I	1	1	1		
※Refer	to timing	chart and	AC timing ch	aracteristi	cs for deta	il					
			posite (howev				n will	not oc	cur even v	vith EXT	COMIN be
			' ISP and EXT								
		be less that		••••••			,		,		
010.10 0.	(
×2 Sett	ting value		,	ization							
	-	e for pixel r	nemory initial		morv meth	od (use	e all c	ear fla	ag or write	all scree	n white)
SCS=Dr	riving acc	o for pixel r ordingly to	nemory initial clear pixel ir	nternal me	mory meth	od (use	e all c	ear fla	ag or write	all scree	n white)
SCS=Dr S1=M2	riving acc (all clear	e for pixel r cordingly to flag) = "H"	nemory initial	nternal me	mory meth	od (use	e all c	ear fla	ag or write	all scree	n white)
SCS=Dr S1=M2 SCLK:	riving acc (all clear Normal	e for pixel r cordingly to flag) = "H" Driving	nemory initial clear pixel ir	nternal me	mory meth	od (use	e all c	ear fla	ag or write	all scree	n white)
SCS=Dr S1=M2 SCLK: [O	riving acc (all clear Normal N Seque	e for pixel r cordingly to flag) = "H" Driving nce]	nemory initial o clear pixel ir or write white	nternal me	mory meth	od (use	e all c	ear fla	ag or write	all scree	n white)
SCS=Dr S1=M2 SCLK: [O (1)	iving acc (all clear Normal N Seque) 5V rise	e for pixel r cordingly to flag) = "H" Driving nce] time (depe	nemory initial o clear pixel ir or write white ends on IC)	iternal me							
SCS=Dr S1=M2 SCLK: [0 (1) (2)	(all clear Normal N Seque) 5V rise	e for pixel r cordingly to flag) = "H" Driving nce] time (depe emory initia	nemory initial o clear pixel ir or write white ends on IC) alization T2	ternal me	nore Initiali	ze with	M2 (a	all clea			
SCS=Dr S1=M2 SCLK: [0 (1) (2)	riving acc (all clear Normal N Seque) 5V rise) Pixel me) Release	e for pixel r cordingly to flag) = "H" Driving nce] time (depe emory initia e time for in	nemory initial o clear pixel ir or write white ends on IC) alization T2 nitialization of	ternal me	nore Initiali tch T3:	ze with 30us	M2 (a s or m	all clea	ar flag) or v	vrite all s	creen whit
SCS=Dr S1=M2 SCLK: [O (1) (2) (3)	iving acc (all clear Normal N Seque) 5V rise) Pixel me) Release Time re	e for pixel r cordingly to flag) = "H" Driving nce] time (depe emory initia e time for in quired to re	nemory initial o clear pixel ir or write white ends on IC) alization T2 nitialization of elease COM	ternal me 1V or m TCOM later related later	nore Initiali: tch T3: ch circuit ir	ze with 30us iitializa	M2 (a s or m	all clea	ar flag) or v	vrite all s	creen whit
SCS=Dr S1=M2 SCLK: [O (1) (2) (3)	iving acc (all clear Normal N Seque) 5V rise) 7V rise) Pixel mo) Release Time re) TCOM p	e for pixel r cordingly to flag) = "H" Driving nce] time (depe emory initia e time for in quired to re colarity init	nemory initial o clear pixel ir or write white ends on IC) alization T2 nitialization of elease COM ialization time	ternal me 1 V or m TCOM later related later T4:	nore Initiali tch T3: ch circuit ir 30us or m	ze with 30us hitializa ore	M2 (a s or m tion w	all clea ore hich is	ar flag) or v s initializing	vrite all s	creen whit
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SCS=Dr S1=M2 SCLK: [O (1) (2) (3) (4) [N	riving acc (all clear Normal N Seque) 5V rise) 7V rise) 7V rise) 7V rise) 7V rise) 7V rise) 7V rise) 700 p Time re ormal Op	e for pixel r cordingly to flag) = "H" Driving nce] time (depe emory initia e time for in quired to re colarity initi quired initi peration]	nemory initial o clear pixel ir or write white ends on IC) alization T2 hitialization of elease COM ialization time alizing TCOM	ternal me 1 V or m TCOM later related later T4:	nore Initiali tch T3: ch circuit ir 30us or m	ze with 30us hitializa ore	M2 (a s or m tion w	all clea ore hich is	ar flag) or v s initializing	vrite all s	creen whit
SCS=Dr S1=M2 SCLK: [O (1) (2) (3) (4) [N Du	riving acc (all clear Normal N Seque) 5V rise) Pixel me) Release Time re) TCOM p Time re ormal Op uration of	e for pixel r cordingly to flag) = "H" Driving nce] time (depe emory initia e time for in quired to re colarity initi quired initi peration] normal dri	nemory initial o clear pixel ir or write white ends on IC) alization T2 hitialization of elease COM ialization time alizing TCOM	ternal me 1 V or m TCOM later related later T4:	nore Initiali tch T3: ch circuit ir 30us or m	ze with 30us hitializa ore	M2 (a s or m tion w	all clea ore hich is	ar flag) or v s initializing	vrite all s	creen whit
SCS=Dr S1=M2 SCLK: [O (1) (2) (3) (4) [N Du [O	riving acc (all clear Normal N Seque) 5V rise) 7V rise	e for pixel r cordingly to flag) = "H" Driving nce] time (depe emory initia e time for in quired to re colarity init quired initi peration] normal dri nce]	nemory initial o clear pixel ir or write white ends on IC) alization T2 nitialization of elease COM ialization time alizing TCOM	ternal me 1 V or m TCOM lat related late T4: 1 polarity a	nore Initiali tch T3: ch circuit ir 30us or m accordingly	ze with 30us hitializa ore to EXT	M2 (a s or m tion w	all clea ore hich is	ar flag) or v s initializing	vrite all s	creen whit
SCS=Dr S1=M2 SCLK: [O (1) (2) (3) (4) [N Dr [O (5)	riving acc (all clear Normal N Seque) 5V rise) 7V rise) Pixel me) Release Time re ormal Op uration of ff Sequei) Pixel me	e for pixel r cordingly to flag) = "H" <u>Driving</u> nce] time (depe emory initia e time for in quired to re colarity init quired initi peration] normal dri nce] emory initia	nemory initial o clear pixel ir or write white ends on IC) alization T2 nitialization of elease COM ialization time alizing TCOM iving	ternal me 1V or m TCOM lat related late T4: 1 polarity a T5:	nore Initialia tch T3: ch circuit ir 30us or m accordingly	ze with 30us nitializa ore to EXT	M2 (a s or m tion w	all clea ore hich is	ar flag) or v s initializing	vrite all s	creen whit
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[Remark] Cautions when powering on

Remark 1) VDD and VDDA should rise simultaneously or VDD should rise first.

Remark 2) VDD and VDDA should simultaneously or VDD should fall first

Table 6-3-1 VDDA=+5.0V, VDD=+5.0V, GND=0V, Tast						=+5.0V、GND=0V、Ta=25°C
Item	Code	MIN	TYP	MAX	Unit	Remark
Frame Frequency	fSCS	1	-	20	Hz	
Clock Frequency	fSCLK		1	2	MHz	
Vertical rush duration	tV	49.993	-	1000	ms	
COM Frequency	fCOM	0.5	-	10	Hz	

Table 6-3-2

VDDA=+5.0V, VDD=+5.0V, GND=0V, Ta=25°C

Item	Code	MIN	TYP	MAX	Unit	Remark
SCS rising time	trSCS			50	ns	
SCS falling time	tfSCS			50	ns	
SCS High width	twSCSH	220			us	Data update mode
		12			us	Display mode
SCS Low width	twSCSL	1			us	
SCS setup time	tsSCS	3			us	
SCS hodl time	thSCS	1			us	
SI rising time	trSI			50	ns	
SI falling time	tfSI			50	ns	
SI set upt time	tsSI	120			ns	
SI hold time	thSI	190			ns	
SCLK rising time	trSCLK			50	ns	
SCLK falling time	tfSCLK			50	ns	
SCLK High width	twSCLKH	200	450		ns	
SCLK Low width	twSCLKL	200	450		ns	
EXTCOMIN signal frequency	fEXTCOMIN		1	20	Hz	[Remark 6-3]
EXTCOMIN signal rising time	trEXTCOMIN			50	ns	
EXTCOMIN signal falling time	tfEXTCOMIN			50	ns	
EXTCOMIN signal High width	twEXTCOMIN	1			us	
DISPrising time	trDISP			50	ns	
DISP falling time	tfDISP			50	ns	

[Remark 6-3] EXTCOMIN frequency should be made lower than frame frequency.

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SCS, SI, SCLK signal	twSCSH //	, twSCSL	
SCS 50%		90% 50% 50% 10% thSCS tfSCS	
SI			
SCLK 10%	50% 50%	50%	
EXTCOMIN signal	fEXTCOMIN		
EXTCOMIN 90% 90% 50% 50% 50% 50% 50% 50% 50% 50% 50% 5	50%	50%	
DISP signal DISP 90% 90% 10%			
* SCS,SI,SCLK、DISP、EXTCOMIN: 3V in	put voltage		



6-4) Power Consumption (Average)

Table 6-4						Ta=25°C
Item	Code	MIN	TYP	MAX	Unite	Remark
Measurement			50		uW	【Remark 6-4】
Condition 1						
Measurement			175		uW	【Remark 6-4】
Condition 2						

*Measurement Condition 1

Display mode (no display data update), Display pattern: Vertical stripe display

*Measurement Condition 2

Data update mode (with display data update: 1Hz)

Common inversion with VDD=5V, VDDA=5V, fSCLK=1MHz, fSCS=1Hz, Display pattern: Vertical stripe display

[Remark 6-4] This is value in steady condition, not the falue of peak power at the time of COM operation. Some marging for power supply is recommended. We recommend capacitor for VDD and VDDA. (If VDD and VDDA are on separate systems, we recommend capacitor for each.)

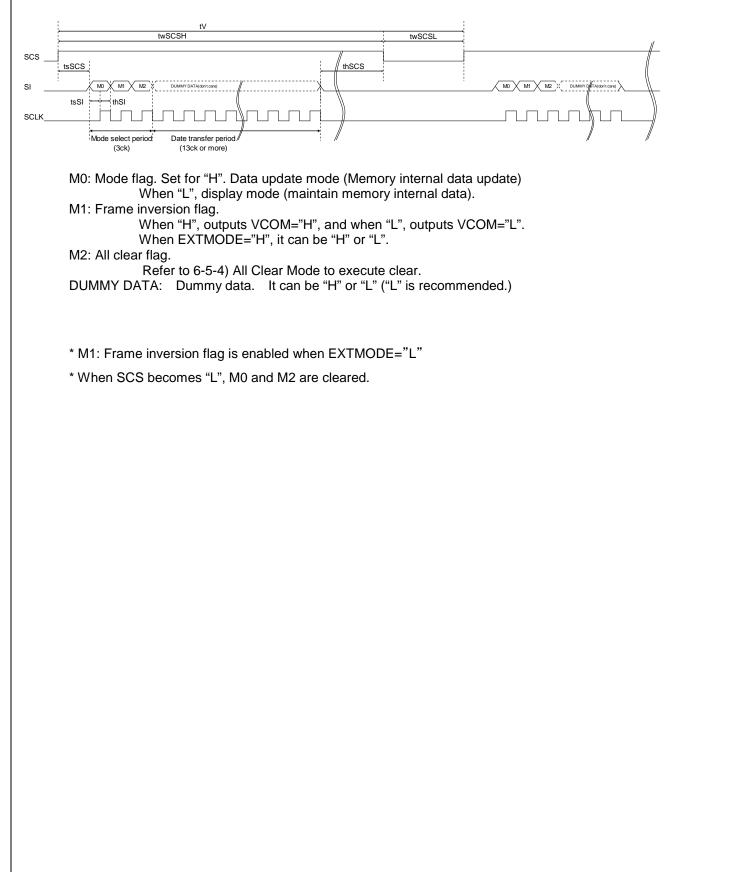
SHARP	SPEC No. LCY-12T09602C	MODEL No. LS027B4DH01	PAGE 14
	LC1-12109002C	L3027 B4DH01	14
6-5) Input Signal Timing Chart			
6-5-1 Data update mode (1 line)			
Updates data of only one specified line. (M0	="H"、M2="L")		
SCS bscs;		thSC	twSCSL
	hunn	DUMMY DATA(don't care)	
M0: Mode flag. Set for "H". Data update When "L", display mode (ma M1: Frame inversion flag. When "H", outputs VCOM="H When EXTMODE="H", it car	intain memory internal of H", and when "L", output	lata).	
M2: All clear flag.			
Refer to 6-5-4) All Clear Mo DUMMY DATA: Dummy data. It can		mmended.)	
 Mata write period Data is being stored in 1 Data transfer period Data written in 1st latch is 		river on panel. ten) to pixel internal memory	circuit.
* For gate line address setting, refer to 6		play.	
* M1: Frame inversion flag is enaled w			
* When SCS becomes "L", M0 and M2 a	are cleared.		

SHARP	SPEC No. LCY-12T09602C	MODEL No. LS027B4DH01	PAGE 15					
6-5-2 Data Update Mode (Multiple Lines) Updates arbitrary multiple lines data. (M0="H	H". M2="I ")							
twscsh								
SCS	uninnn/m	D398 0399 0400 countrarient AGD AG1 AG5 AG D398 0399 0400 countrarient AGD AG1 AG5 AG Date transfer period (8ck(Durmy)+8ck(address)=16ck) GL2nd line						
KuscsH Kuster Kuster <td< td=""><td>period Date transfer pe</td><th></th><td></td></td<>	period Date transfer pe							
M0: Mode flag. Set for "H". Data update When "L", display mode (ma M1: Frame inversion flag. When "H", outputs VCOM="H When EXTMODE="H", it car M2: All clear flag. Refer to 6-5-4) All Clear Mo DUMMY DATA: Dummy data. It can I	intain memory internal of H", and when "L", output h be "H" or "L". de to execute clear.	data). ts VCOM="L".						
X Data transfer period For example, during GL2	Data is being stored in 1 st latch block of binary driver on panel.							
* For gate line address setting, refer to 6	-6) Input Signal and Dis	play.						
* Input data continuously.								
* M1: Frame inversion flag is enabled w								
* When SCS becomes "L", M0 and M2 a	are cleared.							

SHARP

6-5-3 Display Mode

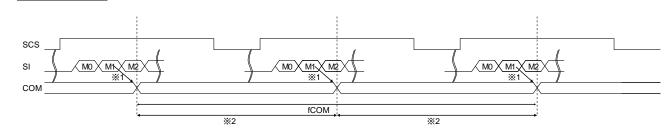
Maintains memory internal data (maintains current display). (M0="L", M2="L")



51	IARP	SPEC No. LCY-12T09602C	MODEL No. LS027B4DH01	PAGE 17
	All Clear Mode s memory internal data and writes white.	(M0="L", M2="H")		
	tV twSCSH	twSCSL		4
SCS	tsSCS thSCS			
SI			M0 M1 M2 X DUMMY DATA(don't care)	<u> </u>
SCLK				
	Mode select period Dummy // (3ck) (13ck or more)	//		//
	M0: Mode flag. Set it "L". M1: Frame inversion flag.			
	When "H", outputs VCOM="H When EXTMODE="H", it can	l", and when "L", outputs be "H" or "L".	s VCOM="L".	
	M2: All clear flag. Set it "H"			
	DUMMY DATA: Dummy data. It can be	e "H" or "L" ("L" is recom	imended.)	
	* M1: Frame inversion flag is enabled v			
	* When SCS becomes "L", M0 and M2	are cleared.		

6-5-5 COM Inversion

There are two types of inputs, COM signal serial input (EXTMODE="L") and external COM signal input (EXTMODE="H"). EXTMODE="L"

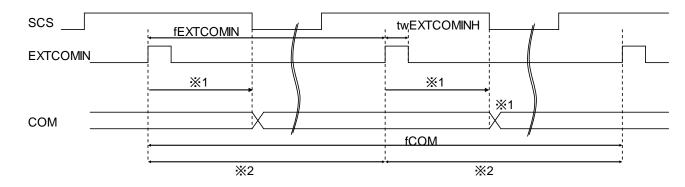


M1:LC polarity inversion flag: If M1is "H" then VCOM="H" is output. If M1 is "L" then VCOM="L" is output.

* 1: LC inversion has been changed by M1 flag statement.

* 2: The periods of plus polarity and minus polarity should be same length as much as possible.

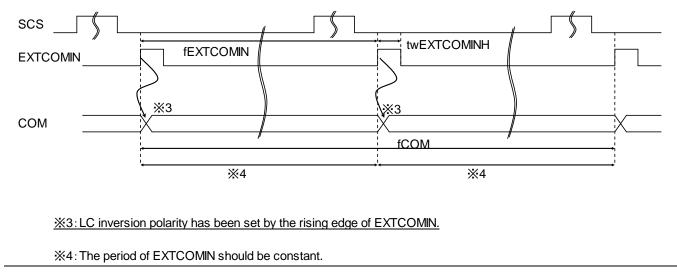
EXTMODE="H"

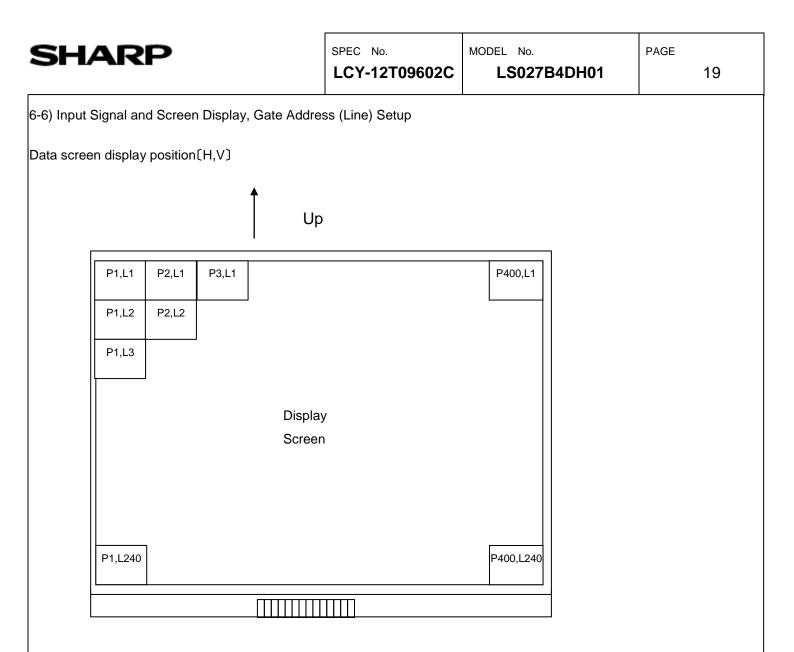


X1: LC inversion polarity has been set by the rising timing of EXTCOMIN in internal circuit block as COMZ signal,

2: The period of EXTCOMIN should be constant.

② EXTCOMIN input when the SCS signals is low.





Gate Line Address Setup								
Line	AG0	AG1	AG2	AG3	AG4	AG5	AG6	AG7
L1	н	L	L	L	L	L	L	L
L2	L	н	L	L	L	L	L	L
L3	Н	H	L	L	L	L	∟	L
		•						
L238	L	н	н	н	L	н	н	н
L239	н	н	н	н	L	Н	н	Н
L240	L	L	L	L	н	н	н	н

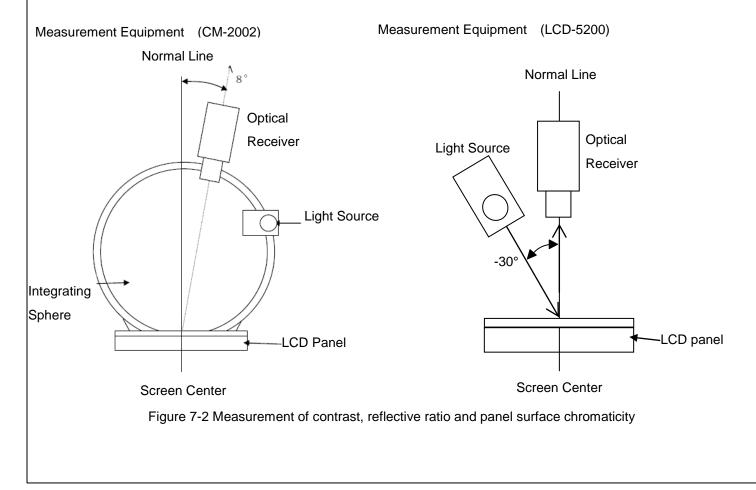


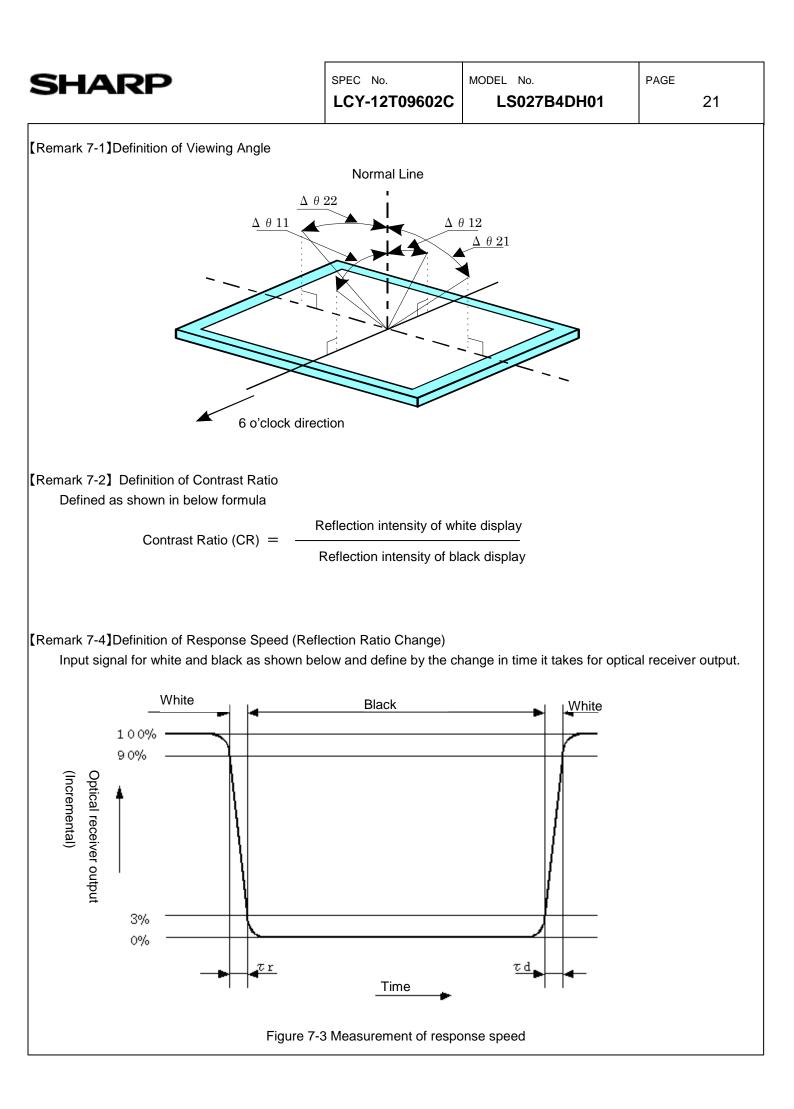
7. Optical Characteristics

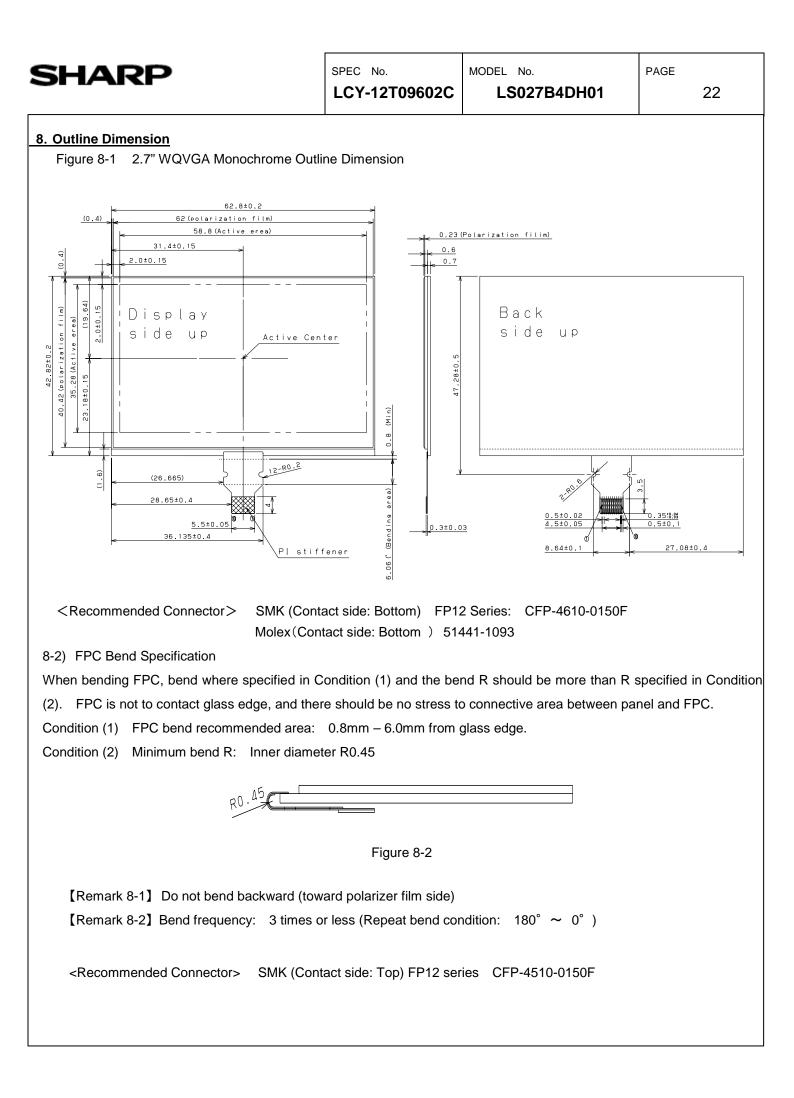
Table 7-1							Ta=25°C
Item		Code	MIN.	TYP.	MAX.	Unit	Remark
Viewing Angle	Н	θ21,θ22	60			°(Degree)	[Remark 7-1]
CR≧2	V	θ11	60			°(Degree)	
		θ12	60			°(Degree)	
Contrast Ratio		CR.		14			【Remark 7-2、 3】
Reflection Ratio		R		18		%	[Remark 7-3]
Response	Rise	τr		10		ms	[Remark
Speed	Fall	τd		20		ms	7-3,4】
Panel Surface	White	х		0.307			[Remark 7-3]
Chromaticity		у		0.330			

[Remark 7-3] Optical Characteristics Measurement Equipment

Contrast ratio, reflective ratio and panel surface chromaticity are measured as shown in figure 7-2, and Response speed is measured as shown in Figure 7-3. Both measurement methods are done in dark Room or equivalent.







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9. External Circuit Example

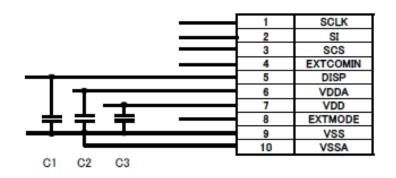


Figure 9-1 External Circuit (Recommended)

- <Recommended Capacitor>
- C1: Between DISP-VSS, B characteristics 0.1uF ceramic capacitor
- C2: Between VDDA-VSS, B characteristics 0.1uF or more cerac capacitor
- C3: Between VDD-VSS, B characteristics 1uF or more ceramic capacitor

*Above circuit and parts are only recommendation.

For actual use, please evaluate their conformity with your system and design.

(Capacitor pressure resistance can be larger than resistance indicated above.)



10. External Power Supply Circuit

An external power supply circuit is necessary to drive the memory LCD with 3V battery. Table 10-1 shows recommended power supply IC>

Table 10-1

Vendor	Model No.	Note	
SII	S-8821	Charge pump type	
National Semiconductor	LM2750	Charge pump type	

[Remark 10-1]For detailed specification, refer to specification for each power supply IC.

[Remark 10-2]To use, set constant value after sufficient evaluation of actual application.

Electrical Characteristics

Table 10-2

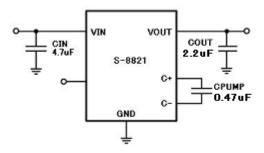
Madal Na	Vin [V]		Vout			lout
Model No.	min	max	min	typ	max	[A]
S-8821	2.8	5.0	4.9	5.0	5.1	0.04
LM2750	2.7	5.6	4.8	5.0	5.2	0.04

[Remark 10-3]For detailed specification, refer to specification for each power supply IC.

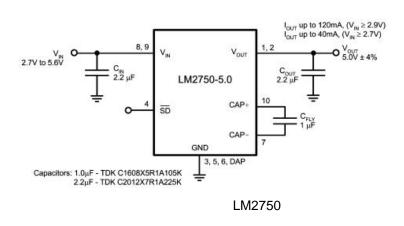
[Remark 10-4]To use, set constant value after sufficient evaluation of actual application.

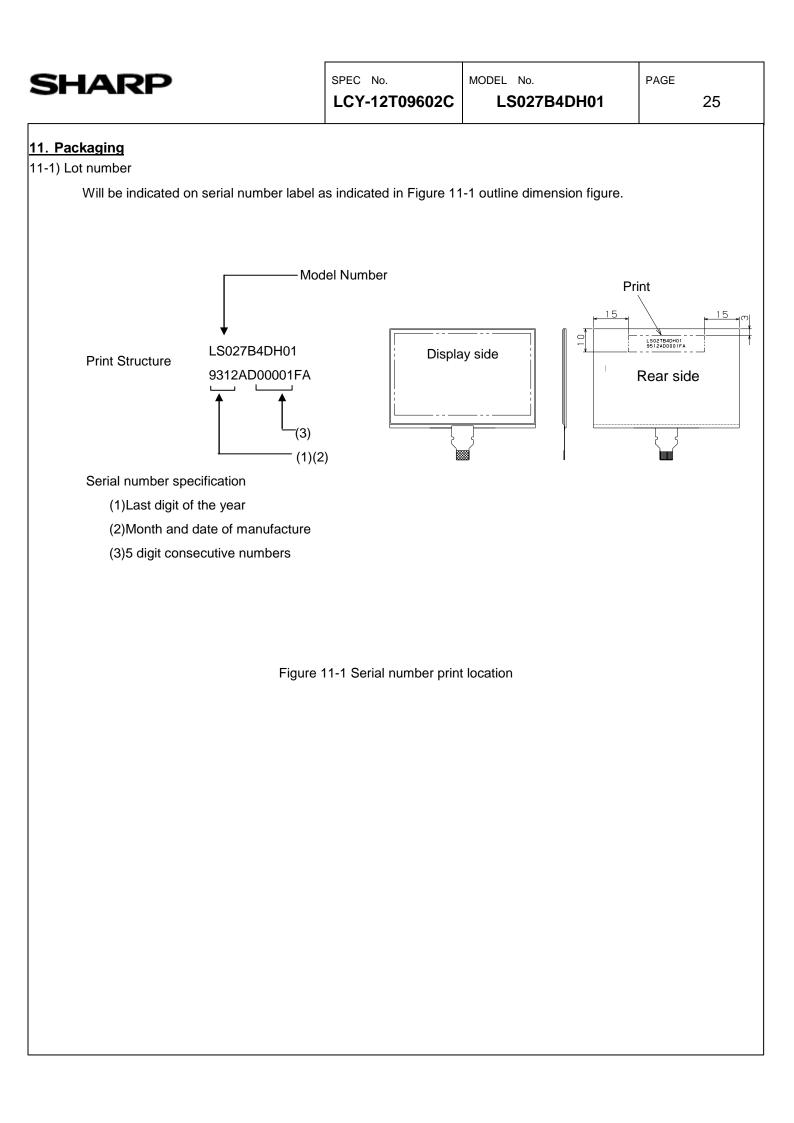
Reference Circuit

Reference circuit is shown below.









SH/	ARP	
SH/	ARP	

11-2) Package Storing

(1)Maximum number of carton in a stack: 12 cartons

Maximum quantity of units in carton: 400 units per carton

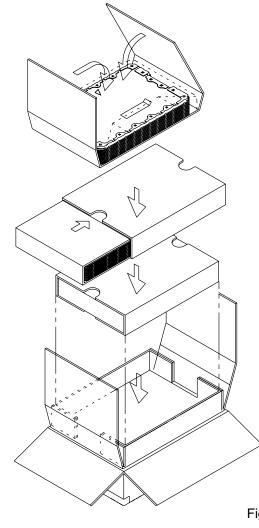
- (2)Storage condition
 - •Temperature: 0 ~ 40°C
 - •Humidity: 60%RH or lower (at 40°C)

There should be no condensation at low temperature and high humidity.

- •Atmosphere: No harmful gas, such as acid or alkali, which causes severe corrosion on electronic parts and wiring are to be detected.
- •Period: About 3 months
- •Opening the package: in order to prevent electrostatic damage to TFT modules, room humidity should be made over 50%RH and take effective measure such as use of earth when opening the package.

11-3) Packaging

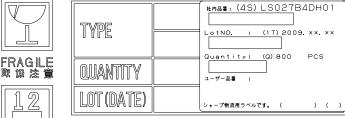
Packaging condition is shown in Figure 11-2.

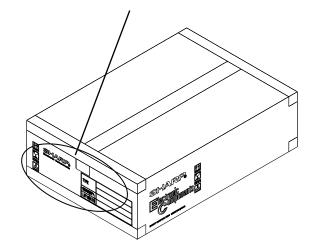












Packageing size :578mmx382mmx153mm





12. Reliability Test Conditions

12-1) Reliability test items

Table 12-1 Reliability test items

	Test items	Test condition	Remark
	High temperature storage	Ta=80°C 240h	
1		(Non-operating)	
	Low temperature storage	Ta=-30°C 240h	
2		(Non-operating)	
	High	Tp=40°C/95%RH 240h	
3	temperature/humidity		
	operation		
4	High temperature	Tp=70°C 240h	
4	operation		
5	Low temperature	Tp=-20°C 240h	
5	operation		
	Heat shock	$Ta=-30^{\circ}C(1h) \sim +80^{\circ}C(1h)/cycle=5cycle$	
6		(Non-operating)	
7	Electrostatic discharge	$\pm 200V$, 200pF(0 Ω) 1 time/each terminal	

[Note] Ta=Surrounding temperature, Tp=Panel temperature

(Evaluation method)

In standard condition, there shall be no practical problems that may affect the display function.

12-2) Panel surface stress specification

"Force of stress [N]" without display failure (display non-uniformity) is defined as follow: Load testing (minimum): 120[N] or higher

Test conditions)	Module:	LCD panel
	Load point:	LCD panel center (glass cloth tape applied in load point area)
	Press jig:	ϕ 10mm cylinder
	Press speed:	1mm/minute
	Support:	Secured on stage
	Press time:	Hold for 5 seconds after reaching test press load and then release